# DSC2G02

# Silicon NPN epitaxial planar type

For high-frequency amplification

#### ■ Features

- $\bullet$  High forward current transfer ratio  $h_{\text{FE}}$  with excellent linearity
- High transition frequency f<sub>T</sub>
- Contributes to miniaturization of sets, reduction of component count.
- Eco-friendly Halogen-free package

## ■ Packaging

Embossed type (Thermo-compression sealing): 3000 pcs / reel (standard)

## ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	V <sub>CBO</sub> 30		
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	20	V	
Emitter-base voltage (Collector open)	$V_{\rm EBO}$	3	V	
Collector current	$I_{C}$	15	mA	
Collector power dissipation	P <sub>C</sub>	200	mW	
Junction temperature	$T_j$	150	°C	
Storage temperature	T <sub>stg</sub>	-55 to +150	°C	

#### ■ Package

• Code

Mini3-G3-B

- Pin Name
  - 1. Base
  - 2. Emitter
  - 3. Collector

#### ■ Marking Symbol: C5

## ■ Electrical Characteristics $T_a = 25$ °C±3°C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	$I_{\rm C} = 10  \mu A, I_{\rm E} = 0$	30			V
Emitter-base voltage (Collector open)	$V_{EBO}$	$I_E = 10 \mu A, I_C = 0$	3			V
Base-emitter voltage	$V_{\mathrm{BE}}$	$V_{CE} = 6 \text{ V}, I_{C} = 1 \text{ mA}$		0.72		V
Forward current transfer ratio *	$h_{FE}$	$V_{CE} = 6 \text{ V}, I_C = 1 \text{ mA}$	65		260	
Transition frequency	$f_T$	$V_{CE} = 6 \text{ V}, I_{C} = 1 \text{ mA}$	450	650		MHz
Reverse transfer capacitance (Common emitter)	C <sub>re</sub>	$V_{CE} = 6 \text{ V}, I_{C} = 1 \text{ mA}, f = 10.7 \text{ MHz}$		0.6		pF
Power gain	PG	$V_{CE} = 6 \text{ V}, I_{C} = 1 \text{ mA}, f = 100 \text{ MHz}$		24		dB
Noise figure	NF	$V_{CE} = 6 \text{ V}, I_{C} = 1 \text{ mA}, f = 100 \text{ MHz}$		3.3		dB

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

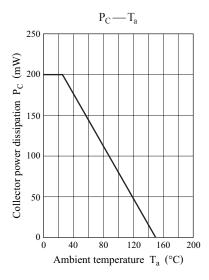
#### 2. \*: Rank classification

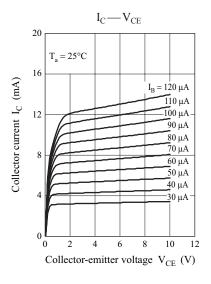
Code	С	D	0
Rank	С	D	No-rank
$h_{\mathrm{FE}}$	65 to 160	100 to 260	65 to 260
Marking Symbol	C5C	C5D	C5

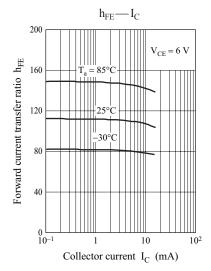
Product of no-rank is not classified and have no marking symbol for rank.

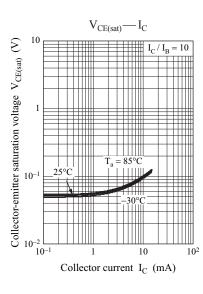
DSC2G02

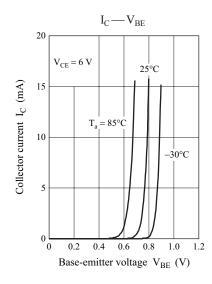
**Panasonic** 

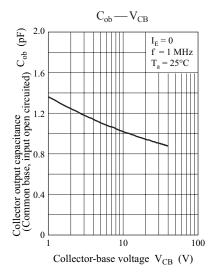


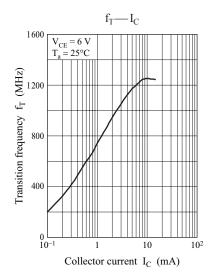








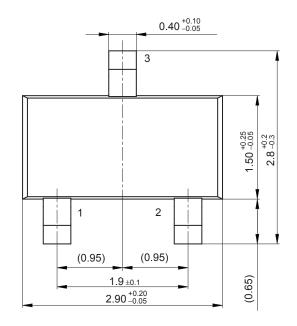


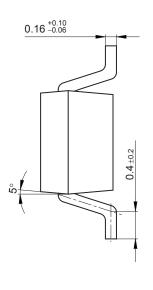


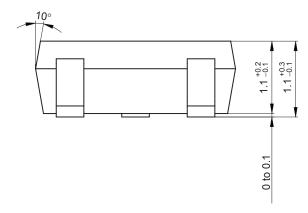
2 Ver. AED

Panasonic DSC2G02

Mini3-G3-B Unit: mm







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